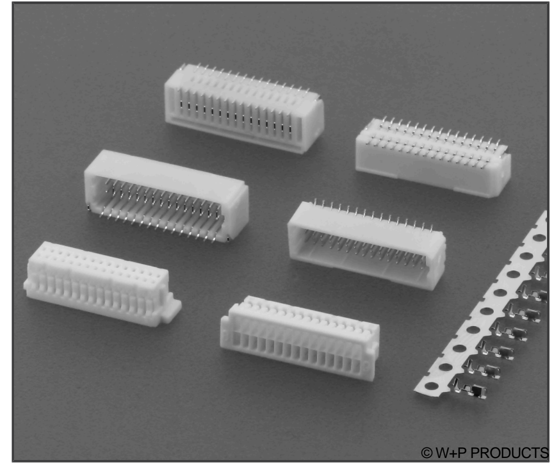
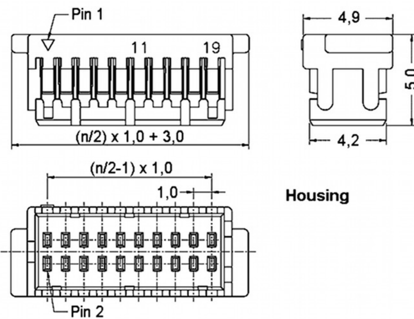
SMT-Crimp-Rast-Stift-/Buchsenleisten RM 1,00mm, stehend/liegend

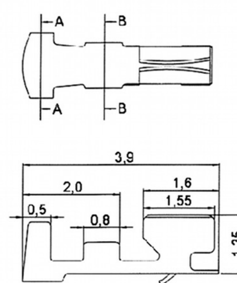
SMT Friction Lock Headers / Crimp Housings, 1.00mm Pitch, Vertical/Horizontal

Technische Daten / *Technical Data*

Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	*Thermoplastic, rated UL94 V-0*
Kontaktmaterial	Kupferlegierung
Contact Material	*Copper alloy*
Aderquerschnitt	AWG 32 ~ 28
Applicable wire Gauge	*AWG 32 ~ 28*
Durchgangswiderstand	< 20 mΩ at initial state
Contact Resistance	*< 20 mΩ at initial state*
Isolationswiderstand	> 100 MΩ
Insulation Resistance	*> 100 MΩ*
Spannungsfestigkeit	500 V AC
Test Voltage	*500 V AC*
Nennspannung	50 V AC
Voltage Rating	*50 V AC*
Nennstrom	1 A mit AWG 28
Current Rating	*1 A with AWG 28*
Temperaturbereich	-25 °C ... +85 °C
Temperature Range	*-25 °C ... +85 °C*
Verarbeitung	Reflow-Lötverfahren
Processing	*Reflow soldering*

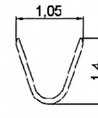


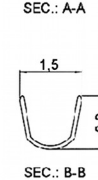


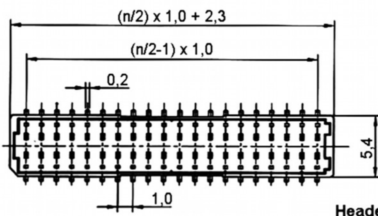


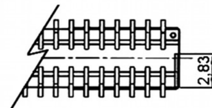
Contact

0,44
0,8

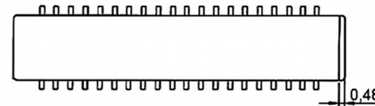


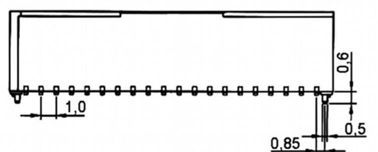


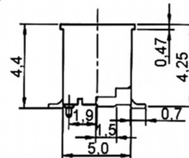


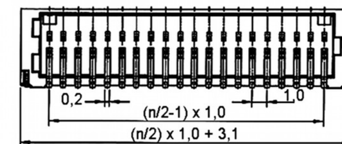


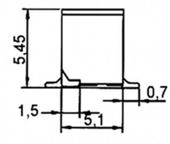
Header - Straight

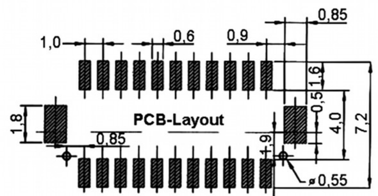


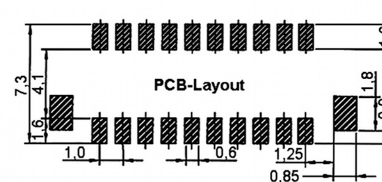












Series	***Contacts****	***Type****	***Plating***
5111	**20**	**3**	**50**
	20/30/40/50 **01** (für Buchsenkontakte) *(for crimp contacts)*	**1** Buchsengehäuse *Housing* **2** Buchsenkontakte *Crimp contacts* **3** Stiftleiste gerade *Straight pin header* **4** Stiftleiste gewinkelt *Right-angled pin header*	**50** Verzinnt (Standard) für Gehäuse nicht erforderlich *Tin plated (Standard)* *(not necessary for housings)*

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
please replace by your specifications.

Design- und technische Änderungen auch ohne vorherige Ankündigung vorbehalten.
Design and/or technical specifications may change without prior notice.

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Informationen zum Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_S$min	150 °C
Temperatur Maximum $T_S$max	200 °C
Dauer $T_S$min – $T_S$max	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_S$max – T_P	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_P$max – $T_S$min	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_S$min	*150 °C*
Maximum Temperatur $T_S$max	*200 °C*
Duration $T_S$min – $T_S$max	*60 – 180s*
Soldering Range Temperature T_L	*217 °C*
Duration above T_L	*60 – 180s*
Ramp-Up Rate $T_S$max – T_P	*max. 3 °C / s*
Peak Temperature T_P	*260±5 °C*
Duration Peak Temperature	*20 – 40s*
Ramp-Down Rate $T_P$max – $T_S$min	*6 °C / s*
Duration 25°C - Peak Temp. T_P	*max. 8min*